



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APG-ABD/13/7713
Dated 18 Feb 2013

**VIPower M05 - Activation of 8" Wafer Fab Catania as
Additional Location**

Table 1. Change Implementation Schedule

Forecasted implementation date for change	31-Jul-2013
Forecasted availability date of samples for customer	11-Feb-2013
Forecasted date for STMicroelectronics change Qualification Plan results availability	11-Feb-2013
Estimated date of changed product first shipment	31-Jul-2013

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	see list
Type of change	Waferfab additional location
Reason for change	Service Improvement
Description of the change	In order to improve Capacities and Service 8 inches wafer Fab Catania has been qualified as additional location for VIPower M05 technology products.
Change Product Identification	"V5" traceability code identify 8" wafer fab
Manufacturing Location(s)	1]Catania Ctm8 2]Catania Ctm6

DOCUMENT APPROVAL

Name	Function
Liporace, Nicola	Marketing Manager
Nicoloso, Riccardo	Product Manager
Minerva, Francesco	Q.A. Manager

VIpower M05: Activation of 8" Wafer Fab. Catania as Additional Location.

WHAT

In order to improve Capacities and Service 8 inches wafer Fab Catania has been qualified as additional location for VIpower M05 technology products.

WHO

All the Customers using below list of products.

Part Number	Samples Availability
VND5004ASP30-E / VND5004ASP30TR-E	wk11-2013
VND5004ATR-E	wk09-2013
VND5004BSP30-E / VND5004BSP30TR-E	wk10-2013
VND5004BTR-E	wk11-2013
VNH5019A-E / VNH5019ATR-E	available
VND5E006ASP-E / VND5E006ASPTR-E	wk32-2013
VN5E010AFH-E / VN5E010AFHTR-E	wk32-2013
VN5E010AHTR-E	wk32-2013
VN5E010MH-E / VN5E010MHTR-E	wk32-2013
VN5E010NAHTR-E	wk32-2013
VN5R003H-E / VN5R003HTR-E	wk32-2013

WHEN

Change will be implemented according to the following schedule:

- Qualification results enclosed to this PCN (RR004111CT6025).
- Samples availability: see upon table.
- Tentative Implementation on July 2013

WHERE

Catania 6" (CT6 – CTM6) / Catania 8" (CM5 – CTM8) .

**VIpower M0L5 technology transfer from
CTM6 Catania (Italy) to CTM8 Catania (Italy)**

General Informations	
Commercial Product	VND5E006ASP-E
Product Line	VH10
Silicon process technology	VIpower M05
Package	PowerSO16

Locations	
Diffusion fab location	ST CTM8 Catania (Italy)
Assembly plant location	ST Muar (Malaysia)
Test plant location	ST Muar (Malaysia)
Reliability lab location	ST Catania (Italy)

General Informations	
Commercial Product	VND5004B-E
Product Line	VH02
Silicon process technology	VIpower M05
Package	PQFN Power 12x12

Locations	
Diffusion fab location	ST CTM8 Catania (Italy)
Assembly plant location	ASE (Korea)
Test plant location	ST Muar (Malaysia)
Reliability lab location	ST Catania (Italy)

Author:

F.CERAULO
Product Qualification Eng
APG Q&R Catania

Reliability and electrical test executed by:

S.Di Stefano - M.Spitaleri
Rel. Eng.
APM Rel Dept. – APG Support

Table of contents

Section	Pag	Content
1	3	Reliability evaluations overview
1.1	3	Objectives
1.2	3	Results
2	4	Traceability
3	6	Devices characteristics VND5006ASP-E
3.1	6	Generalities
3.2	7	Pins connection
3.3	7	Blocks diagram
3.4	7	Bonding diagram
3.5	8	Package outline / Mechanical data
4	9	Devices characteristics VND5004B-E
4.1	9	Generalities
4.2	10	Pins connection
4.3	10	Blocks diagram
4.4	10	Bonding diagram
4.5	11	Package outline / Mechanical data
5	12	Reliability qualification plan and results – Summary table
6	13	Electrical Drift Analysis

- 1. Reliability evaluations overview

1.1 Objectives

Aim of this report is to present the results of the reliability evaluations performed on **VND5E006ASP-E** (VH10 as ST internal silicon line) and on **VND5004B-E** (VH02 as ST internal silicon line) chosen as test vehicles in order to transfer the VIPower M0L5 technology from ST CTM6 Catania (Italy) 6" wafer fab to ST CTM8 Catania (Italy) 8" wafer fab.

These are multi chip Double High Side Driver products with analog current sense for Automotive Application. The **VND5E006ASP-E** is assembled by ST Muar (Malaysia) in PowerSO-16 package while the **VND5004B-E** is assembled by ASE (Korea) subcontractor in QFPN 12x12 package.

The reliability evaluation was based on three lots, two of them of **VND5E006ASP-E** and one of **VND5004B-E**.

According with the **AEC_Q100 Rev.G** specification for the Accelerated Environment Stress (test Group A) and the Accelerated Lifetime Simulation (test Group B) the following tests were performed for each lot: Preconditioning (PC), Temperature Humidity Bias (THB), Autoclave (AC), Thermal Cycling (TC), High Temperature Storage (HTS), Power Temperature Cycling (PTC), High Temperature Operative Life (HTOL). An ESD characterization (HBM, CDM), the Latch-UP (LU) and Gate Leakage (GL) control were also done as Electrical Verification (test Group E).

1.2 Results

All reliability tests have been completed with positive results, neither functional nor parametric rejects were detected at final electrical testing.

The drift analysis performed at $T=+25^{\circ}\text{C}$ examining $I_{\text{OFF}@13V}$, $R_{\text{ON1}@24V}$, $K_{1_CK@16V}$ (for **VND5E006ASP-E**) and $I_{\text{OFF}@13V}$, $R_{\text{ON1}@8V}$ (for **VND5004B-E**), showed a good stability for all the electrical monitored parameters.

Based on the overall positive results we consider the products qualified from a reliability point of view.

- 2. Traceability

VND5006ASP-E

Wafer fab information	
Wafer fab manufacturing location	ST CTM6 CATANIA (Italy) as signal part ST CTM8 CATANIA (Italy) as power die
Wafer diameter	6" as signal part, 8" as power die
Silicon process technology	VIPOWER M05E signal part , VIPOWER M0L5 power die
Die finishing back side	VNS8 (signal) Raw silicon, VNS9 (power) Ti-Ni-Au
Die size	VNS8 (signal) 3160x1690, VNS9 (power) 5780x5210 micron
Metal materials/levels	VNS8 (signal) Ti/TiN/Ti/AlSiCu / 2 levels (3.2 micron last level) VNS9 (power) Ti/TiN/TiAlCu / 1 level (4.7 micron)
Die finishing front side	SiN / Polyimide
Diffusion Lots #	Lot 1: VNS8 (signal) 3104685, VNS9 (power) 5105246 Lot 2: VNS8 (signal) 3117932, VNS9 (power) 5105246

Assembly Information	
Assembly plant location	ST Muar (Malaysia)
Package description	PowerSO_16 FRAME PSO-16 4riv 1-4/5-8fused
Molding compound	SUMITOMO EME-G700LS
Wires bonding materials/diameters	Au 1.3mils (on signal) / Al 12mils (on power)
Die attach material	PREFORM Pb/Ag/Sn 97.5/1.5/1 TAPE ADWILL LE-5000P8AS
Assembly Lots #	Lot1: 991191VS01, Lot2: 991191VT01

Final Testing Information	
Electrical testing manufacturing location	ST Muar (Malaysia)

Reliability Information	
Reliability test execution location	ST Catania (Italy)

VND5004B-E

Wafer fab information	
Wafer fab manufacturing location	ST CTM6 CATANIA (Italy) as signal part ST CTM8 CATANIA (Italy) as power die
Wafer diameter	6" as signal part, 8" as power die
Silicon process technology	VIPower M05E signal part , VIPower M0L5 power die
Die finishing back side	VNS3 (signal) Ti-Ni-Au, VNI4 (power) Ti-Ni-Au
Die size	VNS3 (signal) 2800x1560, VNI4 (power) 7990x4000 micron
Metal materials/levels	VNS3 (signal) Ti/TiN/TiAlCu / 2 levels (3.2 micron last level) VNI4 (power) Ti/TiN/TiAlCu / 1 level (4.7 micron)
Die finishing front side	VNS3 (signal) SiN / Polyimide, VNI4 (power) Teos + PTeos + SiOn + PIX
Diffusion Lots #	VNS3 (signal) 3120430, VNI4 (power) 5105247

Assembly Information	
Assembly plant location	ASE (Korea)
Package description	PQFN Power 12x12
Molding compound	Sumitomo G700
Wires bonding materials/diameters	Au 1.0mils (on signal) / Al 12mils (on power)
Die attach material	PREFORM Pb/Ag/Sn 95.5/2.5/2 D/A ADHESIVE ABLE 8290
Assembly Lots #	HA131CZA21

Final Testing Information	
Electrical testing manufacturing location	ST Muar (Malaysia)

Reliability Information	
Reliability test execution location	ST Catania (Italy)

- 3. VND5E006ASP-E - Devices characteristics

3.1 Generalities



VND5E006ASP-E

Double channel high-side driver with analog current sense
for automotive applications

Features

Max transient supply voltage	V_{CC}	41 V
Operating voltage range	V_{CC}	4.5 to 28 V
Max on-state resistance (per ch.)	R_{ON}	5.5 m Ω
Current limitation (typ)	I_{LMH}	100 A
Off-state supply current	I_S	2 μ A ⁽¹⁾

1. Typical value with all loads connected.

■ General

- Inrush current active management by power limitation
- Very low standby current
- 3.0 V CMOS compatible inputs
- Optimized electromagnetic emissions
- Very low electromagnetic susceptibility
- In compliance with the 2002/95/EC european directive
- Very low current sense leakage

■ Diagnostic functions

- Proportional load current sense
- High current sense precision for wide currents range
- Current sense disable
- Off-state openload detection
- Output short to V_{CC} detection
- Overload and short to ground (power limitation) indication
- Thermal shutdown indication

■ Protections

- Undervoltage shutdown
- Overvoltage clamp
- Load current limitation
- Self limiting of fast thermal transients
- Protection against loss of ground and loss of V_{CC}
- Overtemperature shutdown with auto restart (thermal shutdown)



- Reverse battery protected with self switch of the PowerMOS (see [Figure 32](#))
- Electrostatic discharge protection

Applications

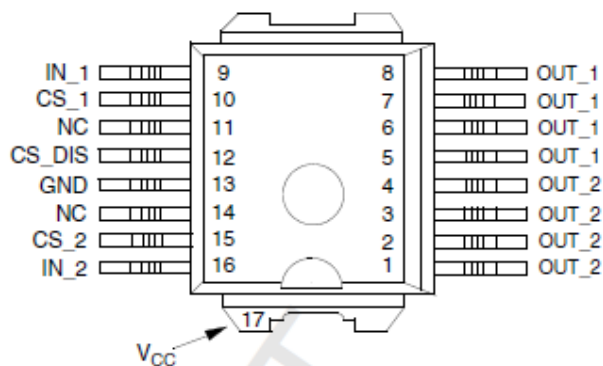
- All types of resistive, inductive and capacitive loads

Description

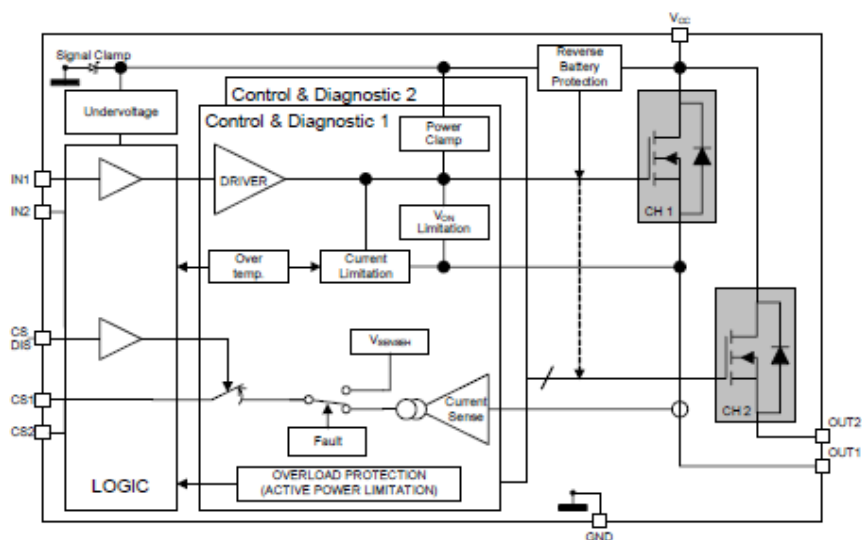
The VND5E006ASP-E is a double channel high-side driver manufactured in the ST proprietary VIPower™ M0-5 technology and housed in the tiny PowerSO-16 package. The VND5E006ASP-E is designed to drive 12 V automotive grounded loads delivering protection, diagnostics and easy 3 V and 5 V CMOS compatible interface with any microcontroller.

The device integrates advanced protective functions such as load current limitation, inrush and overload active management by power limitation, overtemperature shut-off with auto restart and overvoltage active clamp. A dedicated analog current sense pin is associated with every output channel in order to provide enhanced diagnostic functions including fast detection of overload and short-circuit to ground through power limitation indication, overtemperature indication, short-circuit to V_{CC} diagnosis and ON and OFF-state open load detection. The current sensing and diagnostic feedback of the whole device can be disabled by pulling the CS_DIS pin high to allow sharing of the external sense resistor with other similar devices.

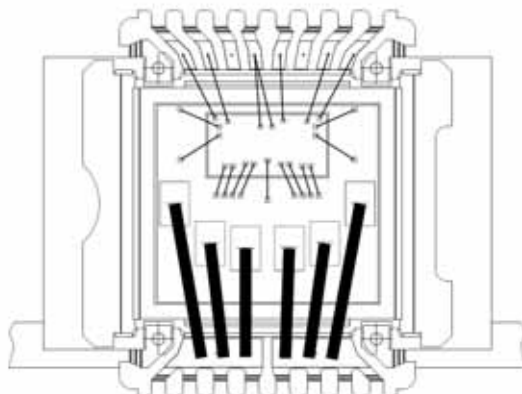
3.2 Pins connection



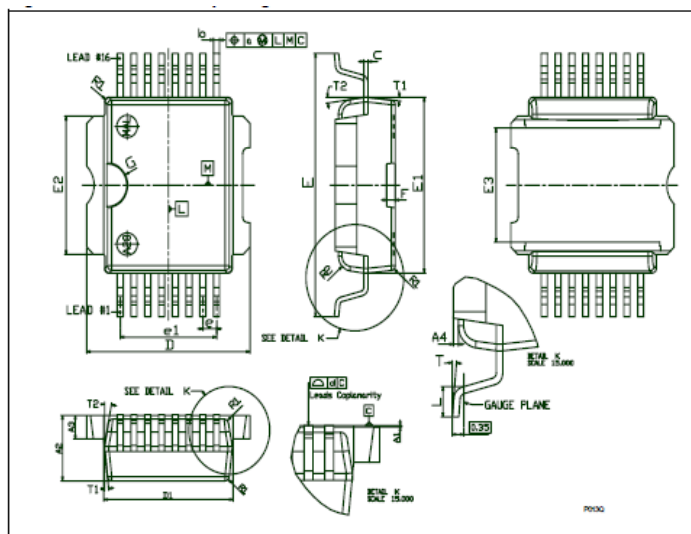
3.3 Blocks diagram



3.4 Bonding diagram



3.5 Package outline/Mechanical data



Dim.	mm		
	Min.	Typ.	Max.
A1	0	0.05	0.1
A2	3.4	3.5	3.6
A3	1.2	1.3	1.4
A4	0.15	0.2	0.25
a		0.2	
b	0.27	0.35	0.43
c	0.23	0.27	0.32
D	9.4	9.5	9.6
D1	7.4	7.5	7.6
d	0	0.05	0.1
E (1)	13.85	14.1	14.35
E1	9.3	9.4	9.5
E2	7.3	7.4	7.5
E3	5.9	6.1	6.3
e		0.8	
e1		5.6	
F		0.5	
G		1.2	
L	0.8	1	1.1
R1			0.25
R2		0.8	
T	2°	5°	8°
T1	6° (typ.)		
T2	10° (typ.)		

- 4. VND5004B-E - Devices characteristics

4.1 Generalities



VND5004B-E **VND5004BSP30-E**

Double 4mΩ high side driver with analog current sense
for automotive applications

Features

Parameters	Symbol	Value
Max transient supply voltage	V _{CC}	41 V
Operating voltage range	V _{CC}	4.5 to 28 V
Max on-state resistance	R _{ON}	4 mΩ
Current limitation (typ)	I _{LIMH}	100 A
Off-state supply current	I _S	2 μA ⁽¹⁾

1. Typical value with all loads connected.

■ General

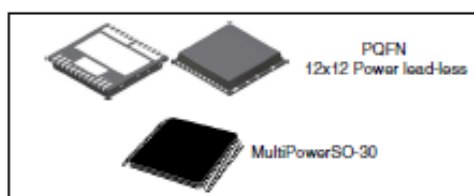
- Inrush current active management by power limitation
- Very low standby current
- 3.0 V CMOS compatible input
- Optimized electromagnetic emission
- Very low electromagnetic susceptibility
- In compliance with the 2002/95/EC European directive

■ Diagnostic functions

- Proportional load current sense
- Current sense disable
- Thermal shutdown indication

■ Protection

- Undervoltage shutdown
- Overvoltage clamp
- Load current limitation
- Thermal shutdown
- Self limiting of fast thermal transients
- Protection against loss of ground and loss of V_{CC}



- Reverse battery protection with self switch on of the Power MOSFET (see [Figure 22](#))
- Electrostatic discharge protection application

- All types of resistive, inductive and capacitive loads

- Suitable for power management applications

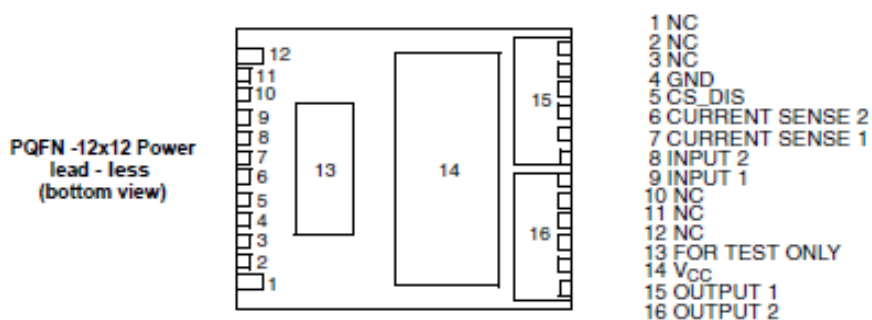
Description

The VND5004BTR-E and VND5004BSP30-E are devices made using STMicroelectronics VIPower technology. They are intended for driving resistive or inductive loads with one side connected to ground. Active V_{CC} pin voltage clamp and load dump protection circuit protect the devices against transients on the V_{CC} pin (see ISO7637 transient compatibility table). These devices integrate an analog current sense which delivers a current proportional to the load current (according to a known ratio) when CS_DIS is driven low or left open. When CS_DIS is driven high, the CURRENT SENSE pin is high impedance. Output current limitation protects the devices in overload condition. In case of long duration overload, the devices limit the dissipated power to a safe level up to thermal shutdown intervention. Thermal shutdown with automatic restart allows the device to recover normal operation as soon as a fault condition disappears.

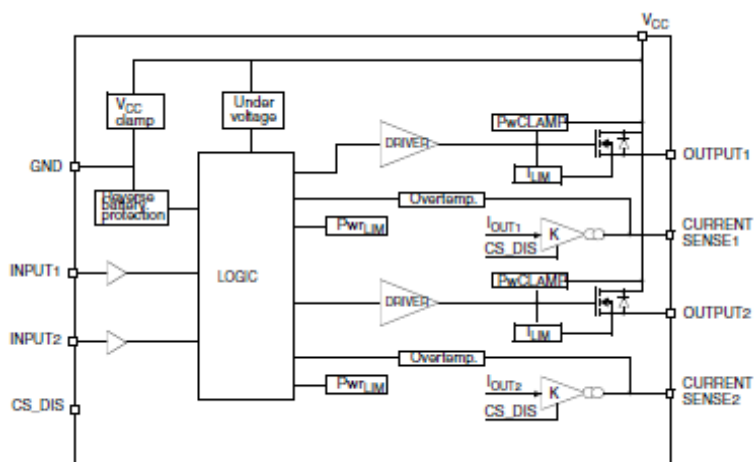
Table 1. Devices summary

Package	Order codes		
	Tube	Tape and reel	Tray
PQFN-12x12 power lead-less	-	VND5004BTR-E	VND5004B-E
MultiPowerSO-30	VND5004BSP30-E	VND5004BSP30TR-E	-

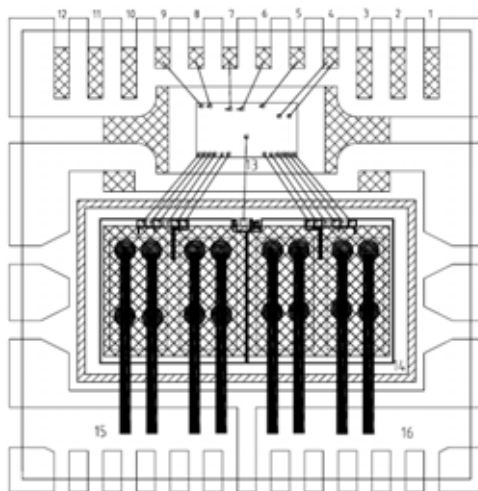
4.2 Pins connection



4.3 Blocks diagram



4.4 Bonding diagram



Technical drawing of a rectangular metal frame. The drawing includes a top view, a side view, and a detail view of the corner. Dimensions are labeled with letters and numbers. The top view shows a rectangular frame with a central opening. The side view shows the profile of the frame. The detail view shows the corner of the frame with dimensions 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42, 43, 44, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 61, 62, 63, 64, 65, 66, 67, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 84, 85, 86, 87, 88, 89, 90, 91, 92, 93, 94, 95, 96, 97, 98, 99, 100.

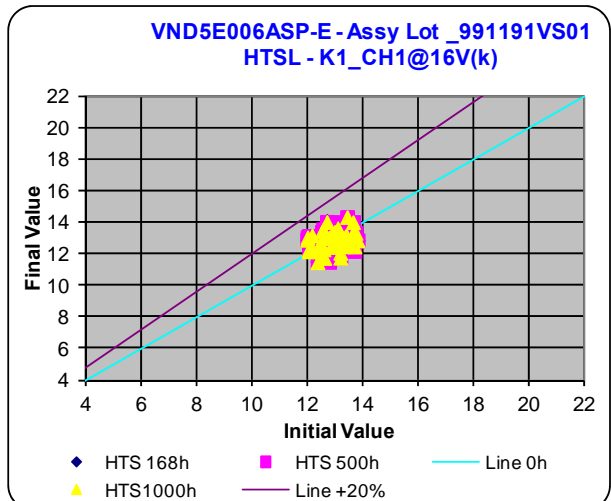
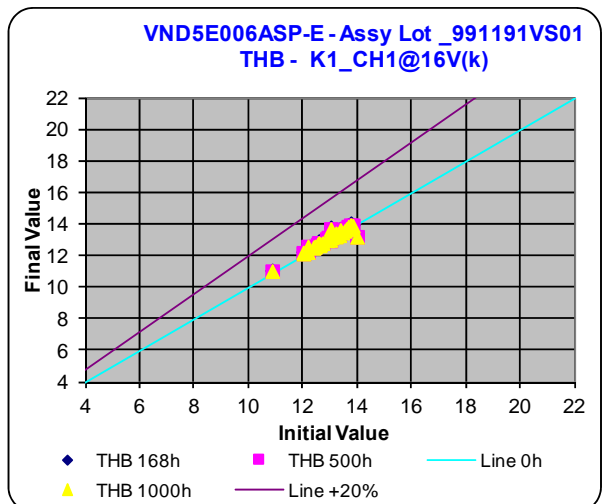
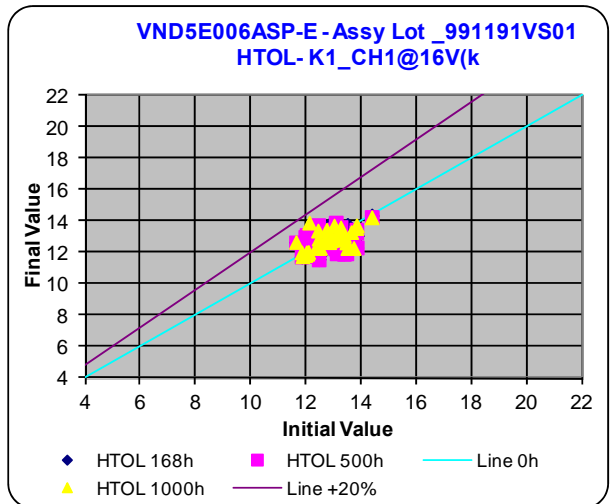
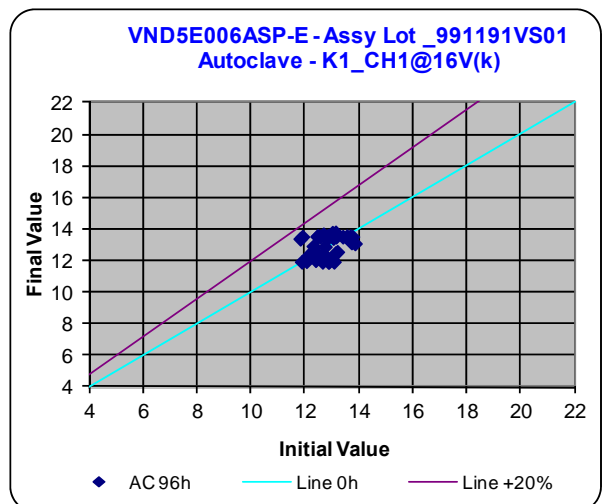
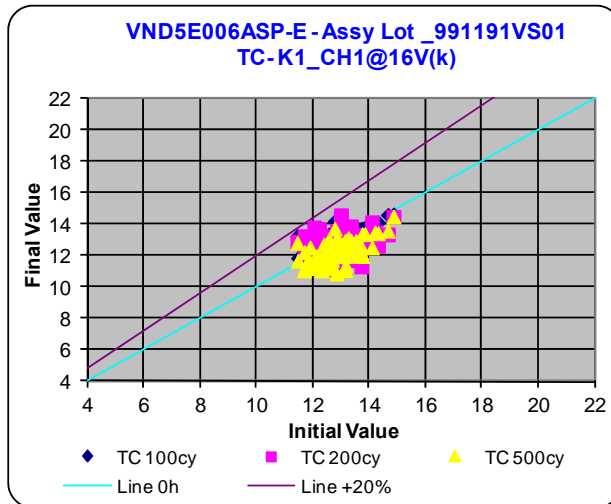
Symbol	Millimeters		
	Min.	Typ.	Max.
A	2		2.2
A1	0		0.05
b	0.35		0.47
C		0.50	
D	11.90		12.10
Dh1	4.65		4.95
Dh2	10.45		10.65
Dh3	4.80		5
Dh4	4.80		5
E	11.90		12.10
Eh1	2.15		2.45
Eh2	5.15		5.45
Eh3	1.70		2
e1		0.90	
e2		3.45	
e3		1.10	
f		0.50	
f1		0.60	
L	0.75		0.95
L1	1.65		1.90
L2	0.76		0.78
M	11.10		11.30
N	11.10		11.30
v		0.1	
w		0.05	
y		0.05	
y1		0.1	

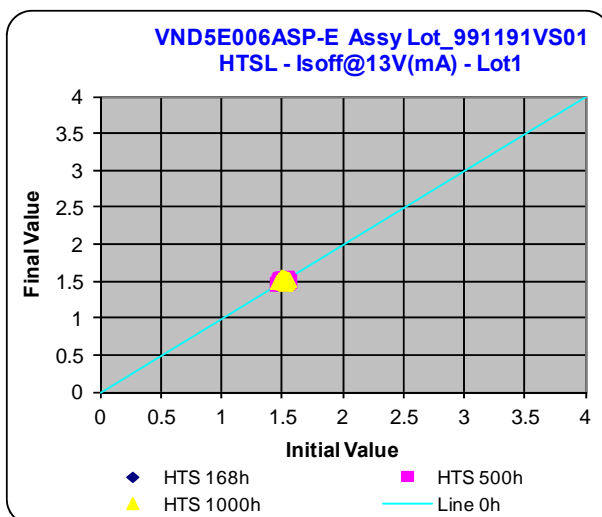
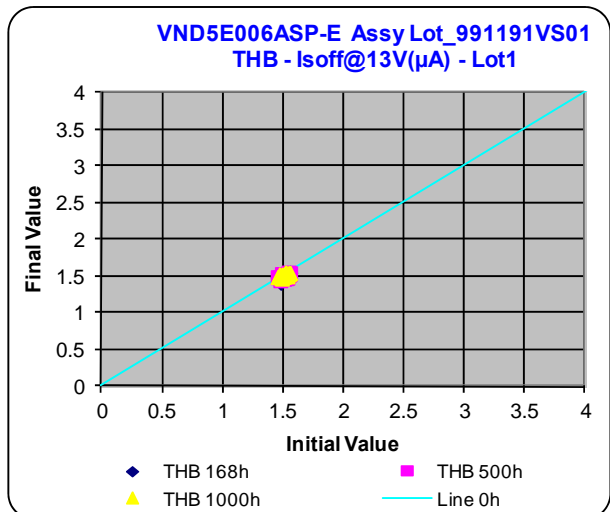
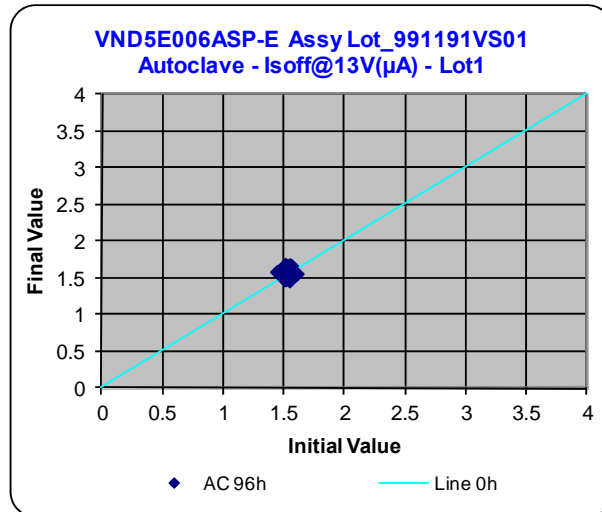
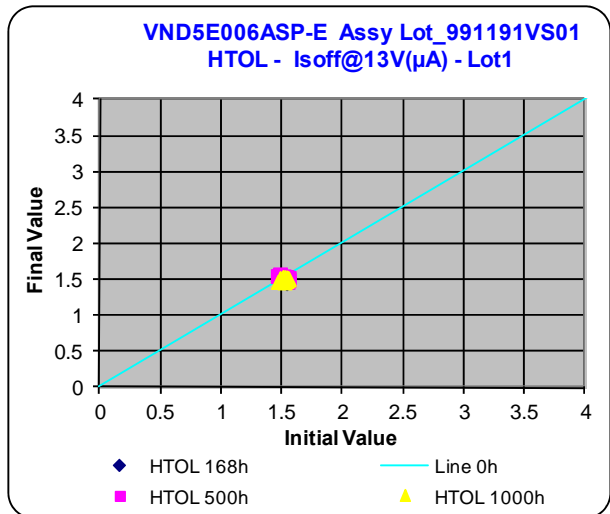
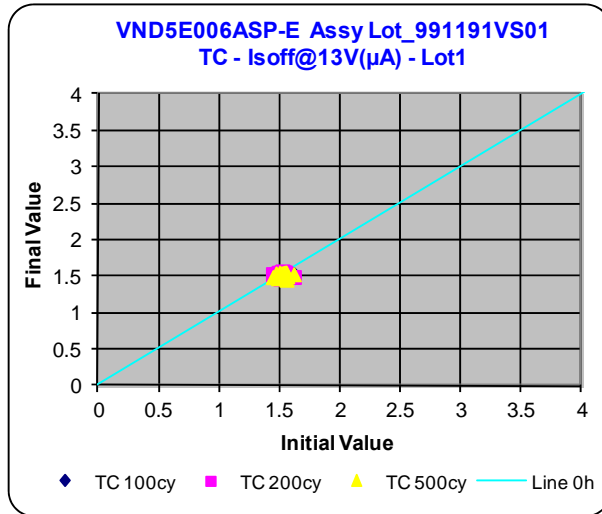
- 5. Reliability qualification plan and results

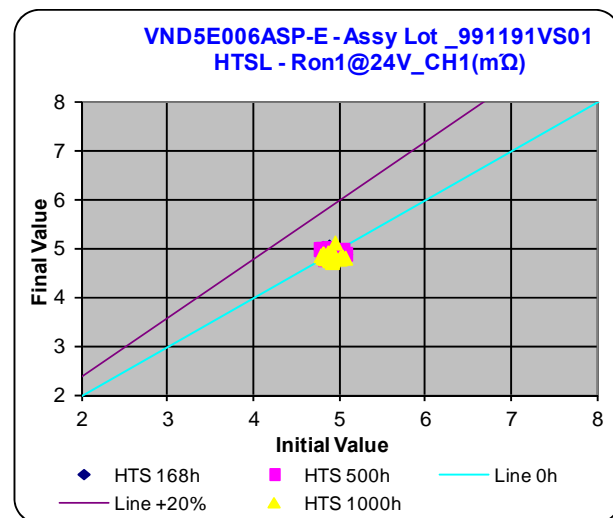
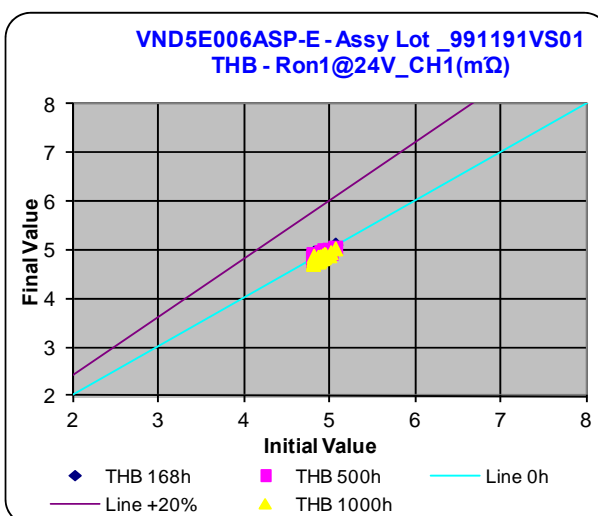
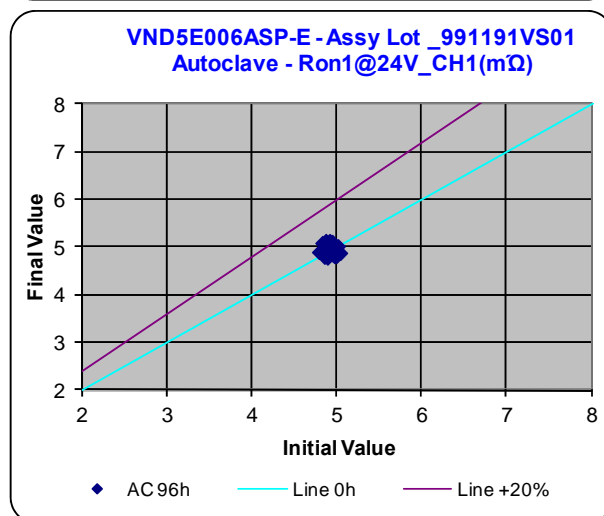
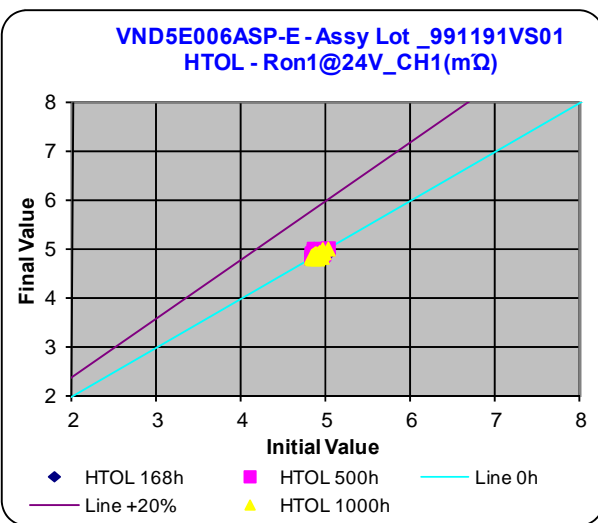
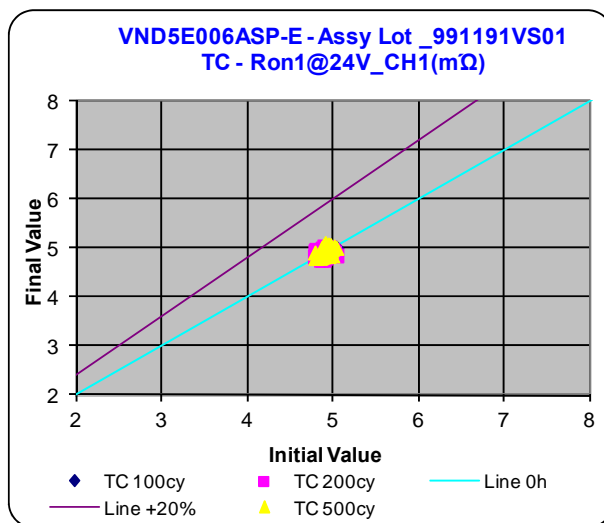
AEC #	Test Name	STM Test Conditions	Sample Size/ Lots	Results Fails/SS/Lots	Comments
A1	PC Pre Cond	Preconditioning at Jedec Level 3, store 192 hours at Ta=30°C, RH=60%, reflow (3 times) at 250°C	Before THB, AC, TC Reliability executed on units soldered on PCB		
A2	THB Temp Humidity Bias	Ta=85°C, RH=85%, V _{CC} =56V for 1000 hours	77/3	0/77/3	2xVND5E006ASP 1xVND5004B
A3	AC Autoclave	Ta=121°C, Pa=2atm, RH=100% for 96 hours	77/3	0/77/3	2xVND5E006ASP 1xVND5004B
A4	TC Temp. Cycling	Ta=-65°C / +150°C for 500 cycles	77/3	0/77/3	2xVND5E006ASP 1xVND5004B
A5	PTC Power Temp. Cycling	Per JA105. Ta=-40°C / +125°C for 1000 cycles. Test before and after at room and hot temperatures.	45/1	0/45/1	Only on VND5E006ASP-E
A6	HTSL High Temp. Storage Life	Ta=150°C for 1000 hours. TST before and after at room and hot temperatures.	45/3	0/45/3	2xVND5E006ASP 1xVND5004B
B1	HTOL High Temp. Op. Life	Bias Static stress (JESD22-A108): Ta=125°C, V _{CC} = 56V for 1000 hours	77/3	0/77/3	2xVND5E006ASP 1xVND5004B
E2	ESD HBM		15/1	V _{CC} /Output: ±5.0kV CS_DIS/Input: ±4.0kV CS: ±2.0kV	Only on VND5E006ASP-E
E2	ESD HBM		3/1	All pins: ±2.0kV	Only on VND5004B-E
E3	ESD CDM		6/1	All pins: ±750V	Both products
E4	LU Latch-Up		6/1	±100mA	
E8	GL Gate Leakage		6/1	Passed	

- 6. Electrical drift analysis

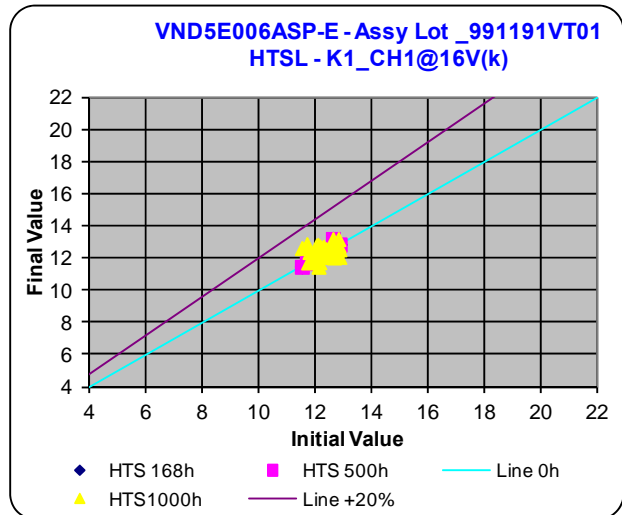
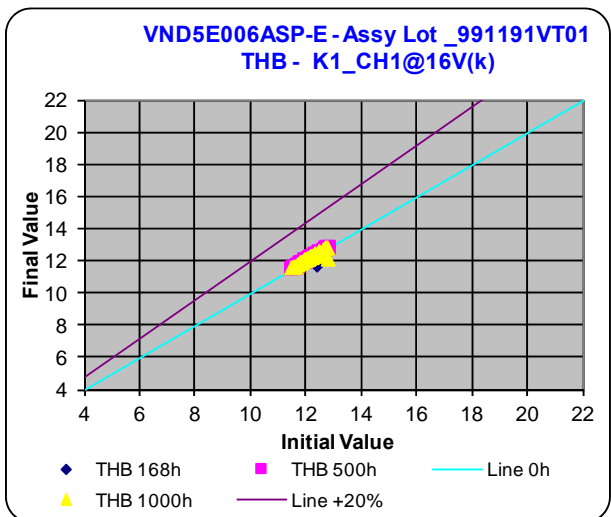
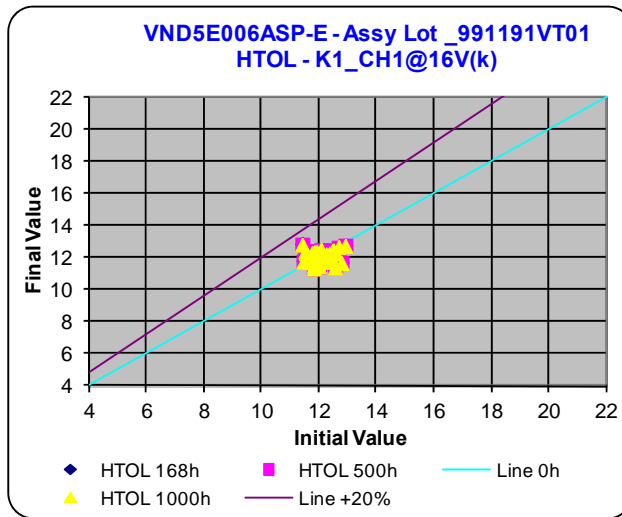
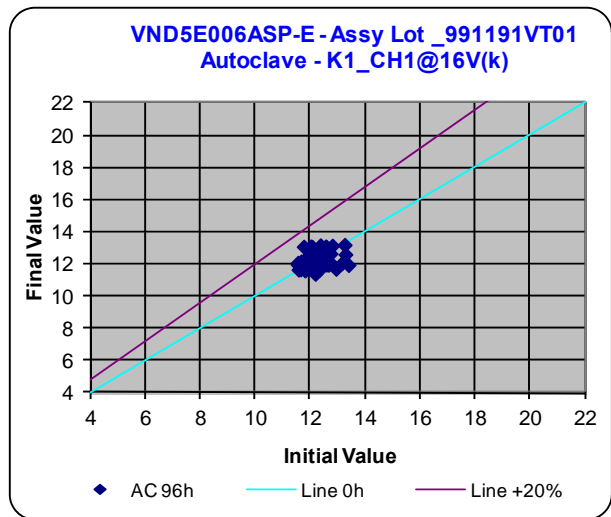
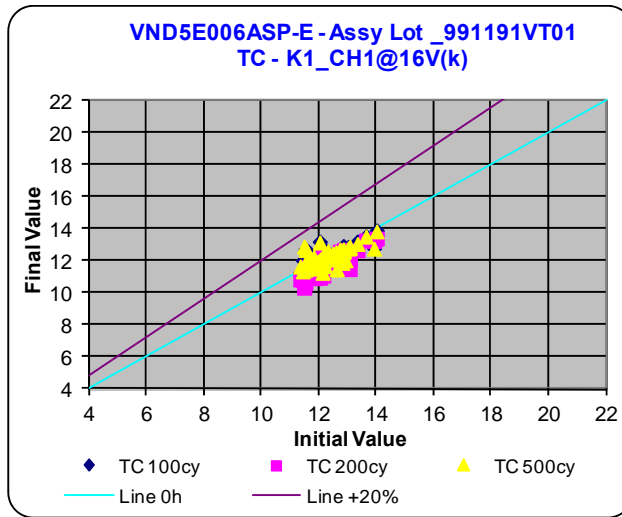
- Assy Lot_991191VS01

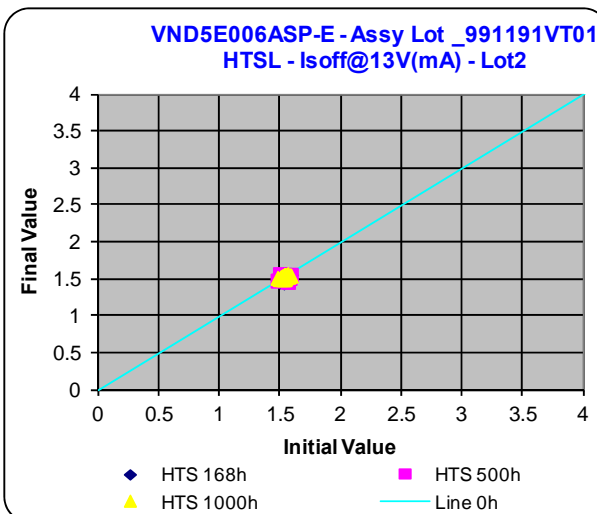
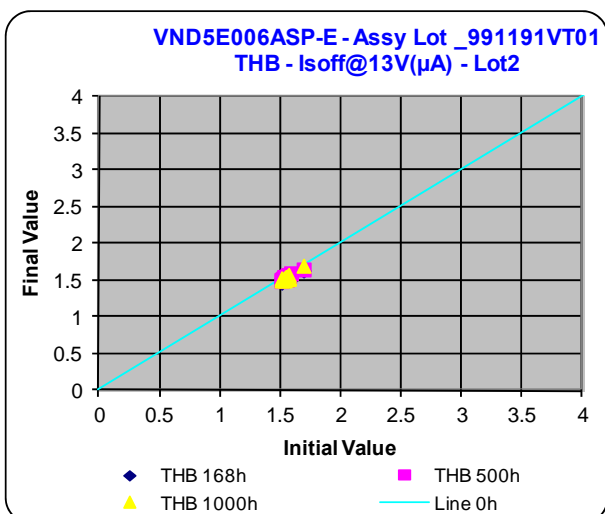
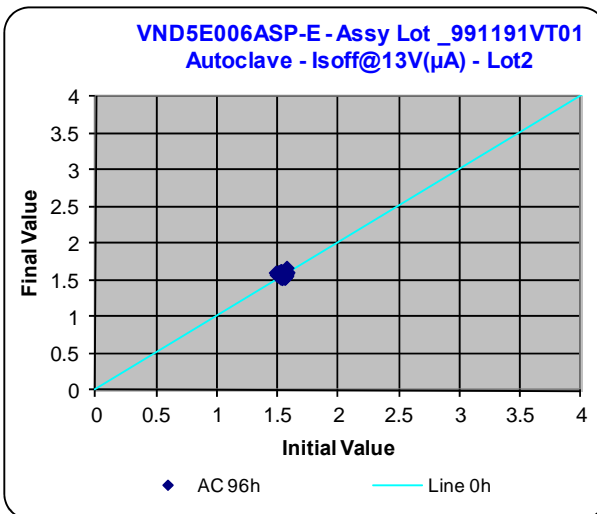
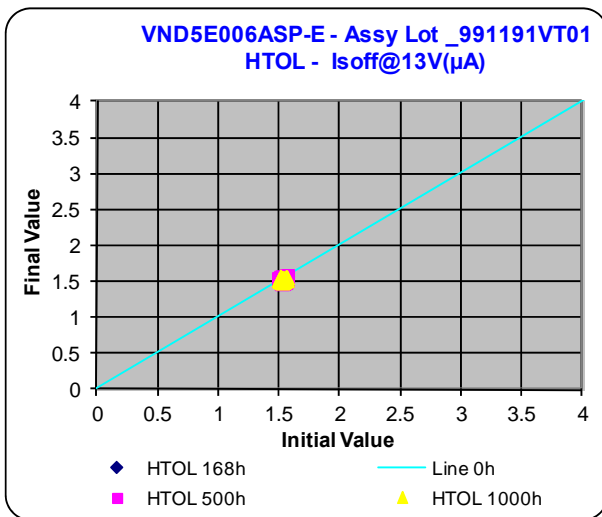
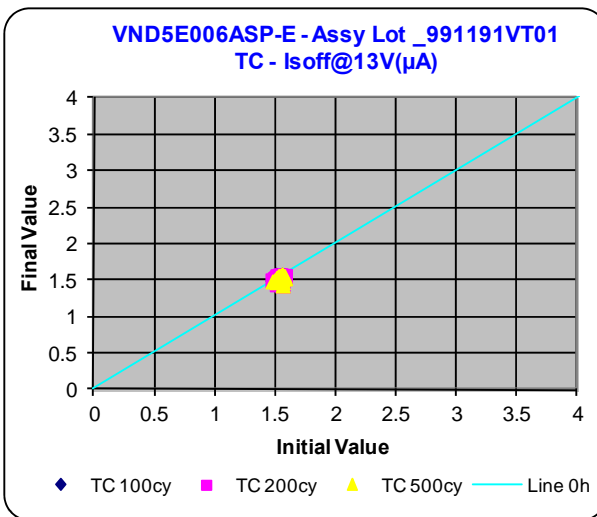


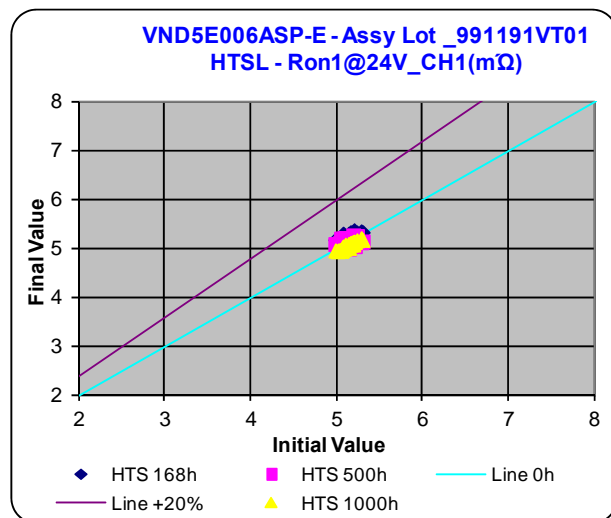
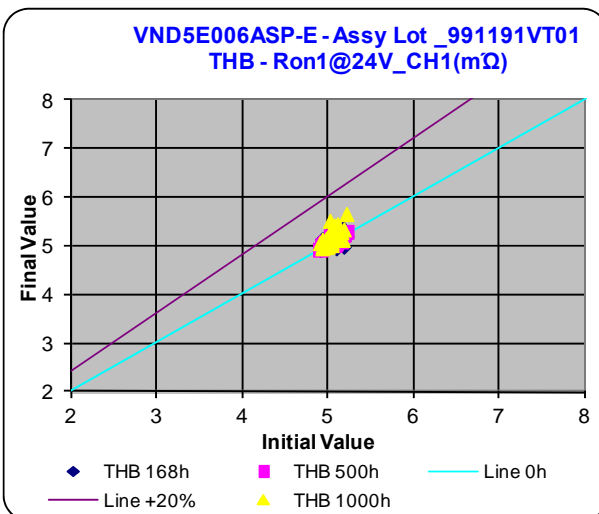
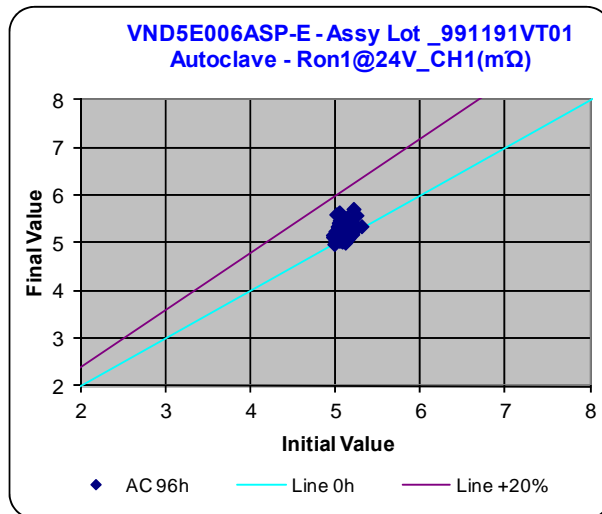
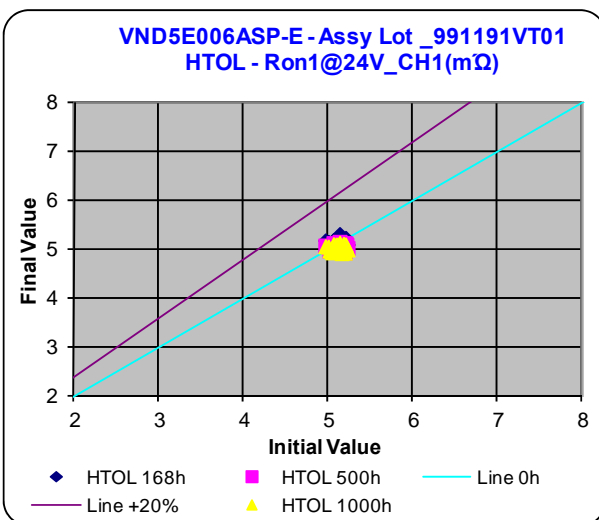
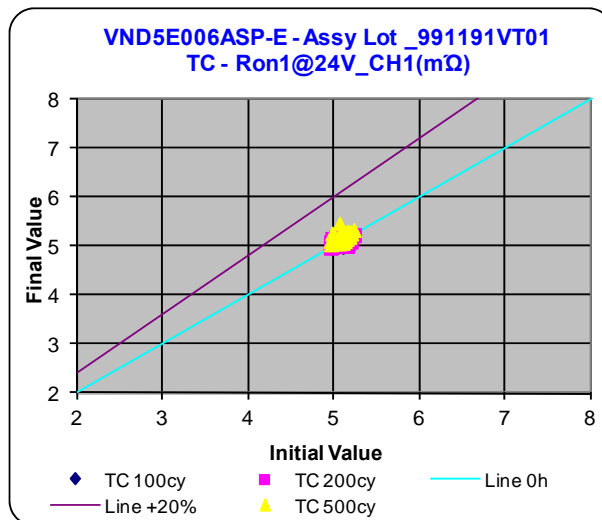




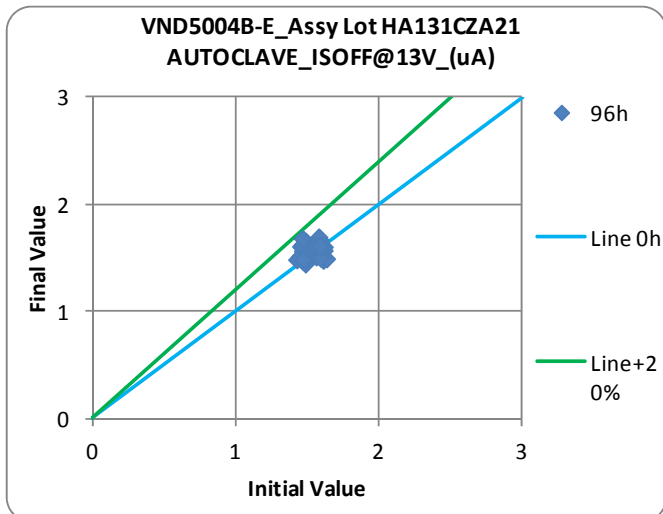
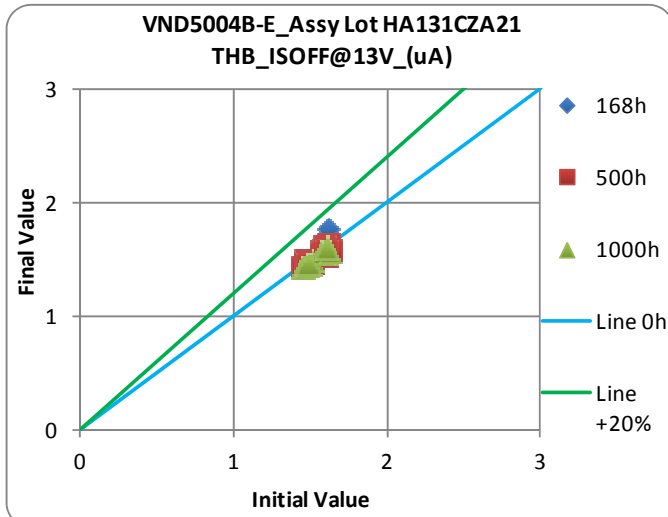
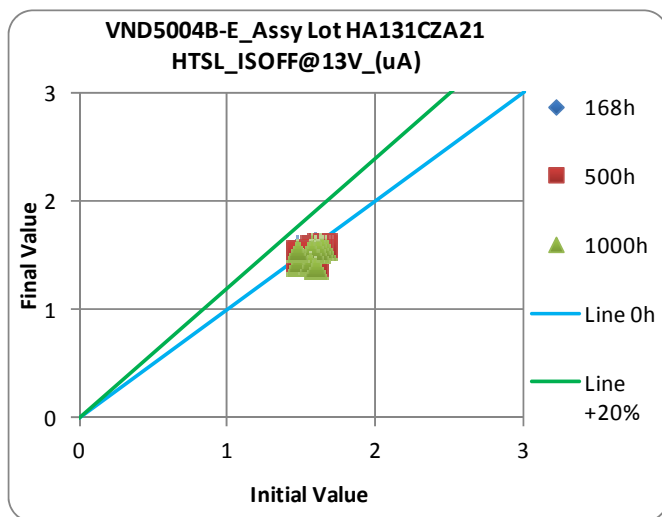
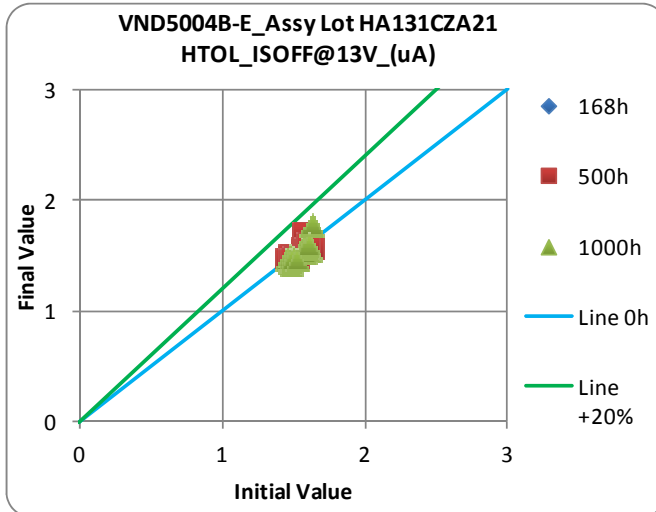
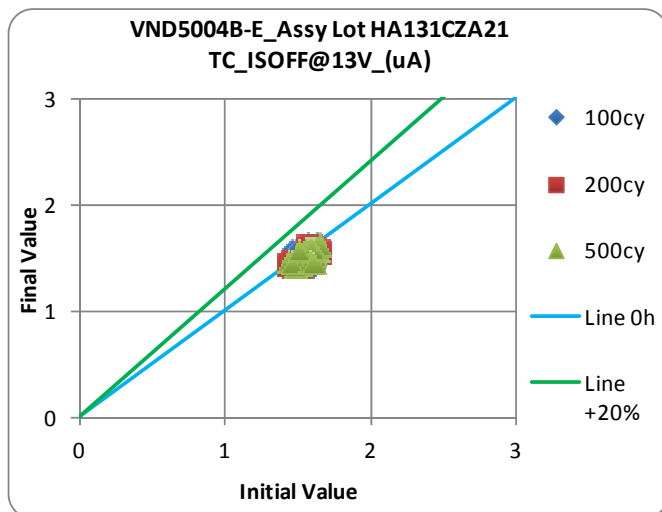
• Assy Lot_991191VT01

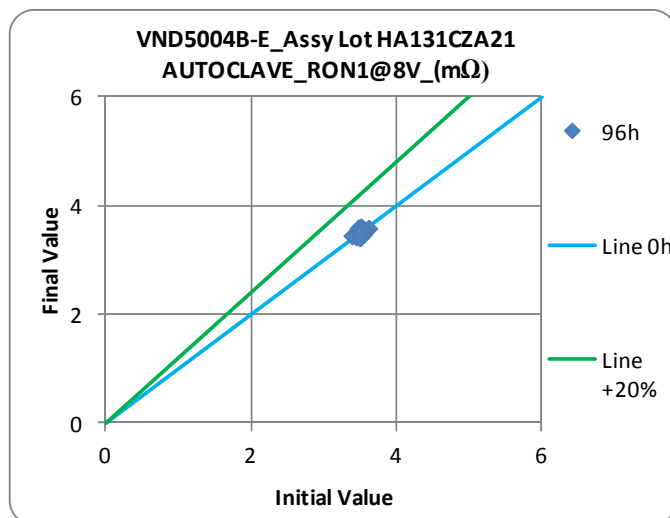
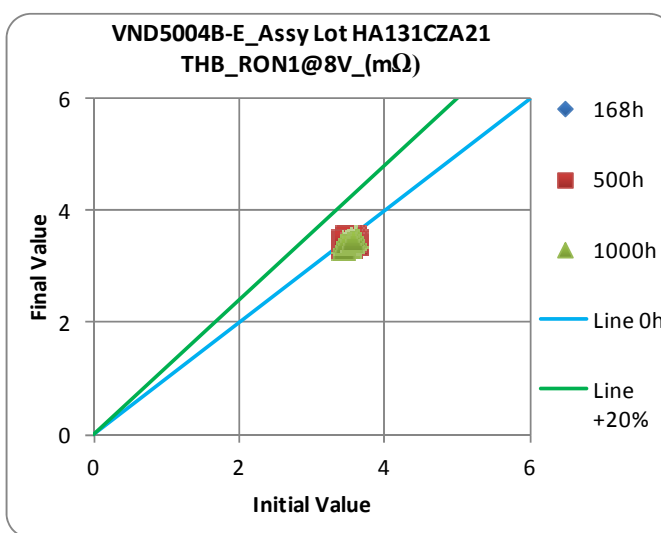
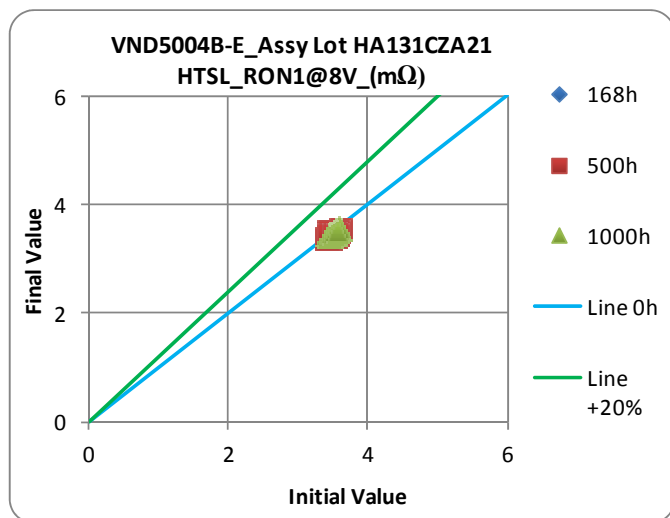
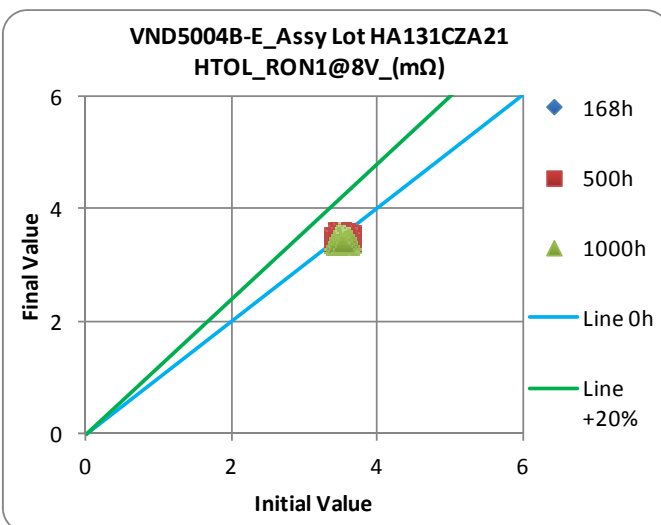
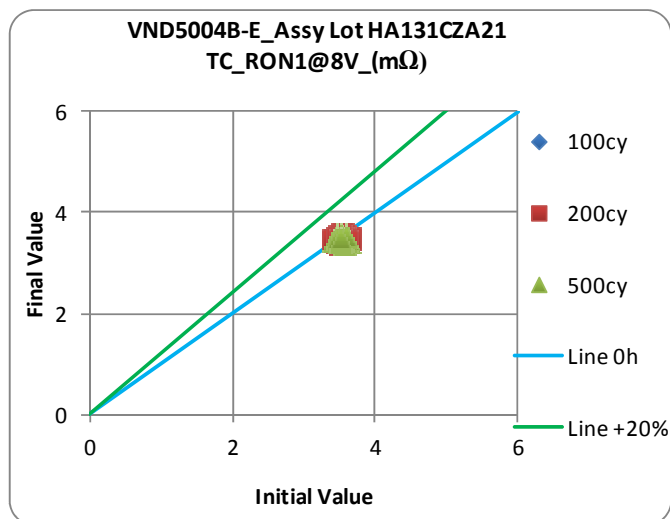






- Assy Lot_HA131CZA21







Public Products List

PCN Title : VIPower M05 - Activation of 8" Wafer Fab Catania as Additional Location

PCN Reference : APG-ABD/13/7713

PCN Created on : 15-FEB-2013

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

VN5E010AHTR-E

VN5R003H-E

VND5004ASP30TR-E

VND5004BSP30TR-E

VND5E006ASPTR-E

VN5E010MH-E

VN5R003HTR-E

VND5004ATR-E

VND5004BTR-E

VNH5019A-E

VN5E010MHTR-E

VND5004ASP30-E

VND5004BSP30-E

VND5E006ASP-E

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY TWO AUTHORIZED ST REPRESENTATIVES, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners

© 2013 STMicroelectronics - All rights reserved.

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -
Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com